



Material Content Data Sheet



Sales Product Name		BSS816NW H6327		Issued		1. August 2018		
MA#		MA001055680						
Package		PG-SOT323-3-2		Weight*		6.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		334	
	noble metal	gold	7440-57-5	0.008	0.13		1295	
	inorganic material	silicon	7440-21-3	0.122	1.98	2.14	19762	21391
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86	
	non noble metal	titanium	7440-32-6	0.003	0.04		429	
	non noble metal	chromium	7440-47-3	0.008	0.13		1288	
	non noble metal	copper	7440-50-8	2.647	42.76	42.94	427669	429472
wire	non noble metal	copper	7440-50-8	0.026	0.42	0.42	4166	4166
encapsulation	organic material	carbon black	1333-86-4	0.030	0.49		4885	
	plastics	epoxy resin	-	0.650	10.50		105022	
	inorganic material	silicondioxide	60676-86-0	2.343	37.86	48.85	378567	488474
leadfinish	non noble metal	tin	7440-31-5	0.133	2.14	2.14	21438	21438
plating	noble metal	silver	7440-22-4	0.217	3.51	3.51	35059	35059
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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